



DESCRIPTION

The JEU05DF3 is an ultra low capacitance transient voltage suppressor array, designed to protect computing applications from the damaging effects of electrostatic discharge and electrical fast transients.

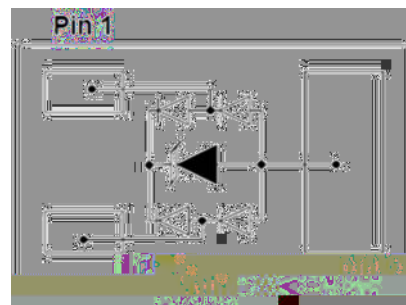


DFN1006-3L

FEATURES

- Protects one uni-directional I/O line

RoHS compliant



Schematic & Pin Configuration
(Top view)

MAIN APPLICATIONS

- Firewire and USB ports
- Display port
- LAN/WAN equipment
- Wireless communications
- Digital visual interface (DVI)
- Microcontroller input protection

PROTECTION SOLUTION TO MEET

- IEC61000-4-2 (ESD) $\pm 15\text{kV}$ (air), $\pm 8\text{kV}$ (contact)
- IEC61000-4-4 (EFT) 40A (5/50ns)
- IEC61000-4-5 (Lightning) 5A (8/20 μs)

MECHANICAL CHARACTERISTICS

- DFN1006-3L package
- Molding compound flammability rating : UL 94V-0
- Quantity per reel : 10,000pcs
- Lead finish : lead free
- Marking code ÖU3

ABSOLUTE MAXIMUM RATINGS ($T_A=25^{\circ}\text{C}$, RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak pulse power dissipation at 8/20 μs waveform	P_{PP}	60	W
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V_{ESD}	+/- 15 +/- 8	kV
Lead soldering temperature	T_L	260 (10 sec.)	
Operating junction temperature range	T_J	-55 to +125	
Storage temperature range	T_{STG}	-55 to +150	

ELECTRICAL CHARACTERISTICS ($T_A=25^{\circ}\text{C}$)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse working voltage	V_{RWM}				5.0	V
Reverse breakdown voltage	V_{BR}	$I_T=1\text{mA}$	6.0			V
Reverse leakage current	I_R	$V_{RWM}=5\text{V}$			1.0	μA
Peak pulse current	I_{PP}	$t_P=8/20\mu\text{s}$			5	A
Clamping voltage	V_C	$I_{PP}=5\text{A}$, $t_P=8/20\mu\text{s}$		13	15	V
Junction capacitance	C_J	$V_{RWM}=0\text{V}$, $f=1\text{MHz}$ Between I/O			0.8	pF

RATINGS AND V I CHARACTERISTICS CURVES ($T_A=25^{\circ}\text{C}$, unless otherwise noted)

FIG.1: V - I curve characteristics (Uni-directional)

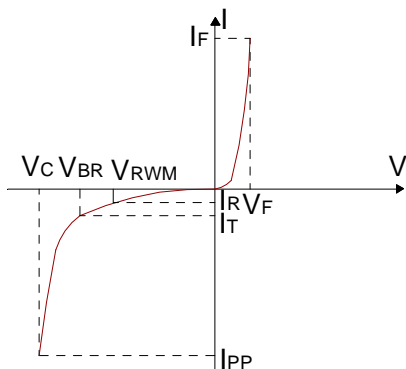


FIG.2: Pulse waveform (8/20 μs)

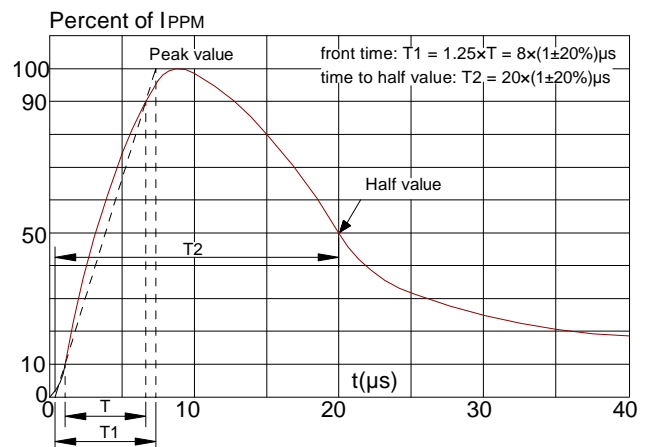




FIG.3: Pulse derating curve

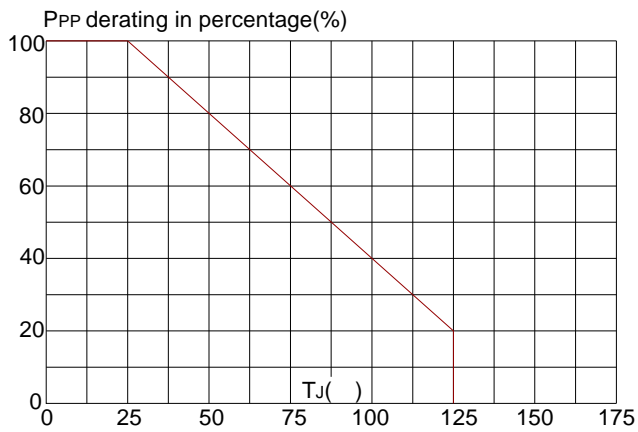
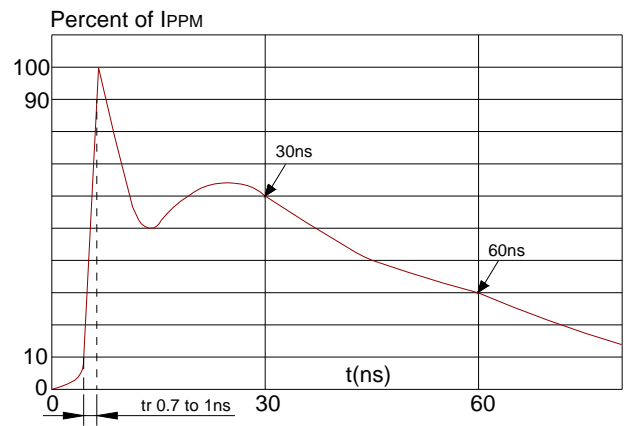


FIG.4: ESD clamping (8KV contact)



SOLDERING PARAMETERS

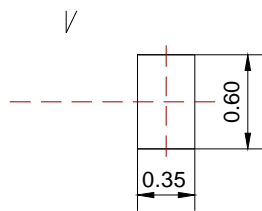
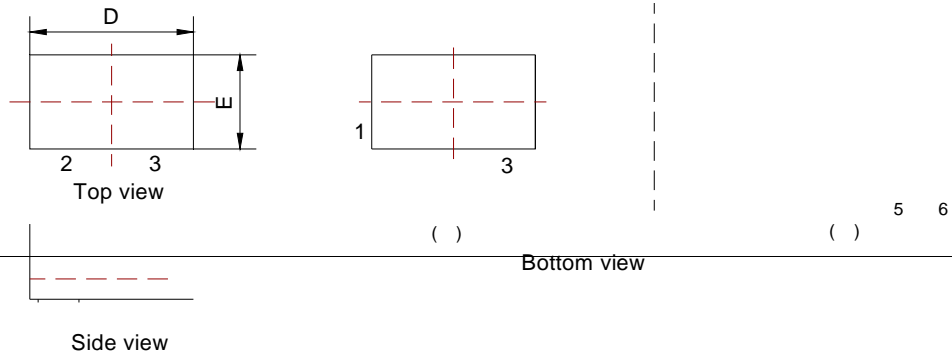
Reflow Condition		Pb-Free assembly (see figure at right)
Pre Heat	-Temperature Min (T _{s(min)})	+150
	-Temperature Max(T _{s(max)})	200
	-Time (Min to Max) (ts)	60-180 secs.

(T_L)to peak

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PACKAGE MECHANICAL DATA



Recommended soldering footprint(mm)

JEU05DF3

